



**Synchronous Buck
Multiphase Optimized BGA Power Block
Integrated Power Semiconductors, Drivers & Passives**

Features:

- 20A continuous output current with no derating up to $T_{PCB} = 90^\circ\text{C}$
- Very small 11mm x 11mm x 3mm footprint
- Internal features minimize layout sensitivity *
- Optimized for very low power losses
- 5 to 12V input voltage

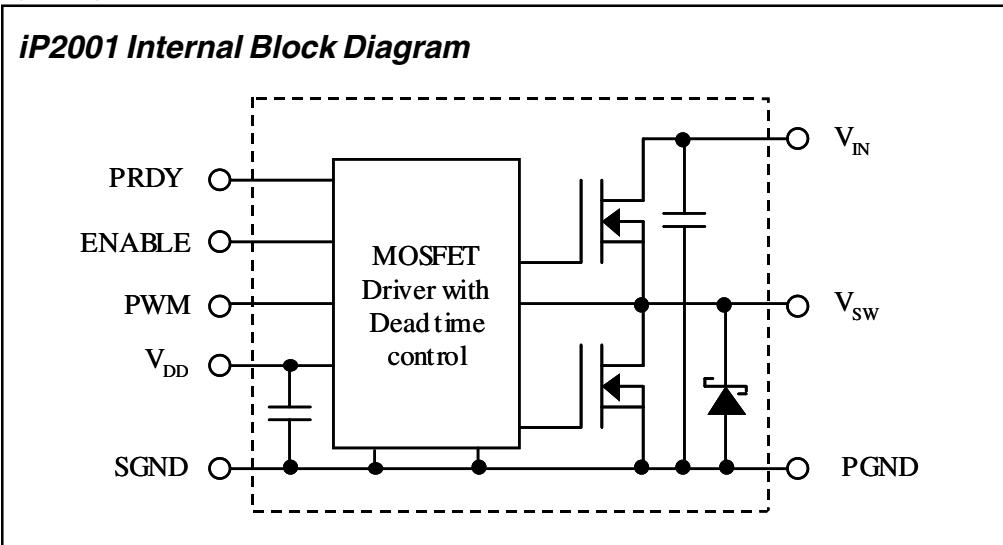


iP2001 Power Block

Description

The iP2001 is a fully optimized solution for high current synchronous buck multiphase applications. Board space and design time are greatly reduced because most of the components required for each phase of a typical discrete based multiphase circuit are integrated into a single 11mm x 11mm x 3mm BGA power block. The only additional components required for a complete multiphase converter are a PWM IC, the external inductors plus the input and output capacitors.

iPOWIR technology offers designers an innovative board space saving solution for applications requiring highest power density. iPOWIR technology eases design for applications where component integration offers benefits in performance and functionality. iPOWIR technology solutions are also optimized internally for layout, heat transfer and component selection.



* All of the difficult PCB layout and bypassing issues have been addressed with the internal design of the iPOWIR Block. There are no concerns about double pulsing, unwanted shutdown, or other malfunctions which often occur in switching power supplies. The iPOWIR Block will function normally without any additional input power supply bypass capacitors. However, for reliable long term operation it is recommended that the adequate amount of input decoupling is provided on the V_{IN} pin. No additional bypassing is required on the V_{DD} pin.

iP2001

All specifications @ 25°C (unless otherwise specified)

Absolute Maximum Ratings :

| Parameter | Min | Typ | Max | Units | Conditions |
|---------------------|------|-----|-----|-------|------------|
| V_{IN} to PGND | - | - | 16 | V | |
| Sw Node to PGND | -0.3 | - | 17 | V | |
| Output RMS Current | - | - | 20 | A | |
| V_{DD} to SGND | - | - | 6.0 | V | |
| DRV_IN to SGND | -0.3 | - | 6.0 | V | |
| Enable to SGND | -0.3 | - | 6.0 | V | |
| Storage Temperature | -40 | - | 125 | °C | |

Recommended Operating Conditions :

| Parameter | Symbol | Min | Typ | Max | Units | Conditions |
|----------------------|-----------|------|-----|------|-------|------------|
| Supply Voltage | V_{DD} | 4.5 | 5.0 | 5.5 | V | |
| Input Voltage Range | V_{IN} | 4.75 | - | 12.6 | V | |
| Output Voltage Range | V_{OUT} | 0.9 | - | 2.0 | V | |
| Output Current Range | I_{OUT} | - | - | 20 | A | see Fig.2 |
| Operating Frequency | fsw | 150 | - | 1000 | kHz | see Fig. 2 |

Electrical Specifications @ $V_{DD} = 5V$ (Unless otherwise specified) :

| Parameter | Symbol | Min | Typ | Max | Units | Conditions |
|---------------------------------------|----------------|-----|-----|-----|-------|---|
| Block Power Loss ① | P_{BLK} | - | 3.1 | 3.8 | W | $f_{sw}=500\text{kHz}$, $V_{IN}=12\text{V}$, $I_{OUT}=20\text{A}$ |
| Turn On Delay ② | $t_{d(on)}$ | - | 63 | - | ns | $I_{OUT}=20\text{A}$, $V_{OUT}=1.6\text{V}$, $f_{sw}=500\text{kHz}$, $V_{IN}=12\text{V}$ |
| Turn Off Delay ② | $t_{d(off)}$ | - | 26 | - | ns | |
| V_{IN} Quiescent Current | I_{Q-VIN} | - | - | 1.0 | mA | Enable=0V, $V_{IN}=12\text{V}$ |
| V_{DD} Quiescent Current | I_{Q-VDD} | - | - | 10 | μA | Enable=0V, $V_{DD}=5\text{V}$ |
| Under Voltage Lockout Start Threshold | UVLO | | | | | |
| | V_{START} | 4.2 | 4.4 | 4.6 | V | |
| Hysteresis | $V_{Hys-UVLO}$ | - | .05 | - | V | |
| Enable | Enable | | | | | |
| Input Voltage High | V_{IH} | 2.0 | - | - | V | |
| Input Voltage Low | V_{IL} | - | - | 0.8 | V | |
| Power Ready | PRDY | | | | | |
| Logic Level High | V_{OH} | 4.5 | 4.6 | - | V | $V_{DD}=4.6\text{V}$, $I_{Load}=10\text{mA}$ |
| Logic Level Low | V_{OL} | - | 0.1 | 0.2 | V | $V_{DD}=\text{UVLO Threshold}$, $I_{Load}=10\text{μA}$ |
| Drive Input | DRV_IN | | | | | |
| Logic Level High | V_{OH} | 2.0 | - | - | V | |
| Logic Level Low | V_{OL} | - | - | 0.8 | V | |

① Measurement were made using four 10uF (TDK C3225X7R1C106M or equiv.) capacitors across the input. See Figs. 1 & 3.

② Not associated with the rise and fall times. Does not affect Power Loss (see Fig 4).

Pin Description Table

| Pin Name | Ball Designator | Pin Function |
|-----------------|---|---|
| V _{DD} | A1 – A3, B1 – B3 | Supply voltage for the internal circuitry. |
| V _{IN} | A5 – A12, B5 – B12, C5 - C10 | Input voltage for the DC-DC converter. |
| PGND | C11, C12, D11, D12, E11, E12, F6, F7, F12, G6, G7, G12, H6, H7, H12, J6, J7, J12, K5 – K7, K12, L5, L6, L12, M5 – M7, M12 | Power ground - Connection to the ground of bulk and filter capacitors. |
| V _{SW} | D5 – D10, E5 – E10, F8 – F11, G8 – G11, H8 – H11, J8 – J11, K8 – K11, L8 – L11, M8 – M11 | Switching node - Connection to the output inductor. |
| SGND | C1 – C3, D1 – D3, E1 – E3 | Signal Ground. |
| ENABLE | F1 | When set to logic level high, internal circuitry of the device is enabled. When set to logic level low, the PRDY pin is forced low, the internal circuitry is disabled and the supply current is less than 10µA. |
| PRDY | K1 | Power Ready - This pin indicates the status of V _{DD} . When V _{DD} is less than 4.4V(typ.), this output is driven low. When V _{DD} is greater than 4.4V(typ.), this output is driven high. This output has a 10mA source and 10µA sink capability. |
| PWM | H1 | TTL-level input signal to MOSFET drivers. |
| NC | B4, C4, D4, E4, F2 – F4, G2 – G4, H2 – H4, J1, J2 – J4, K3, L1, L2, M1 – M4 | This pin is not for electrical connection. It should be attached only to dead copper for thermal conductive routing. |

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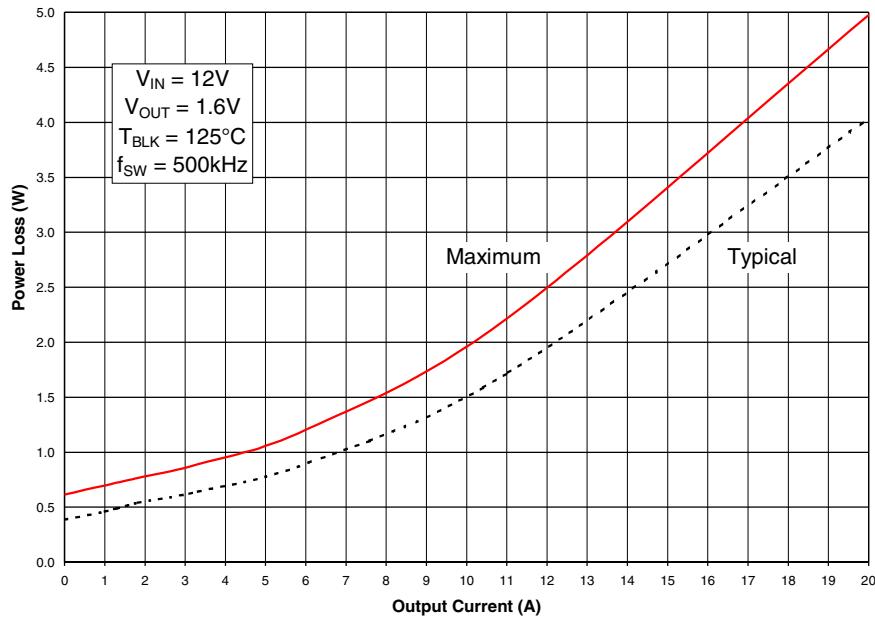


Fig 1. Power Loss vs. Current

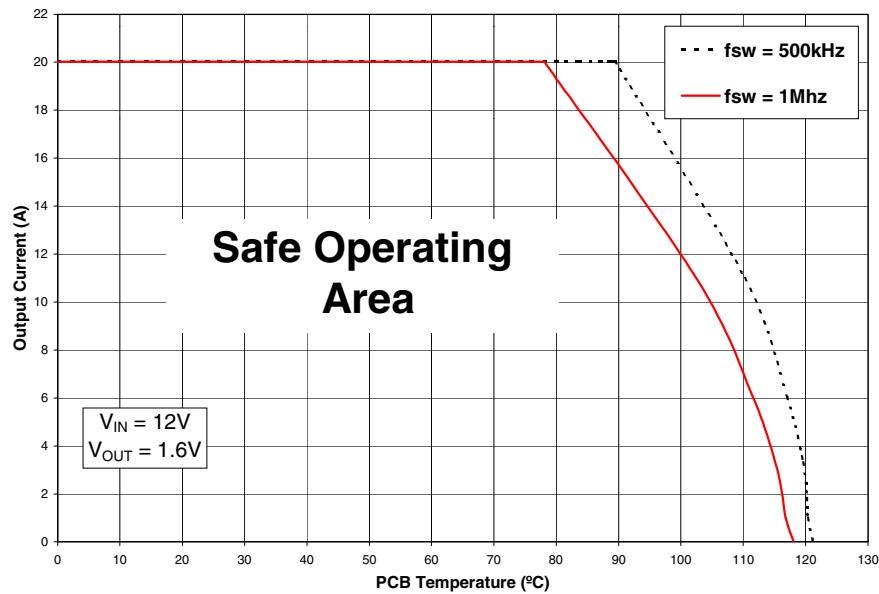


Fig 2. Safe Operating Area (SOA) vs. T_{PCB}

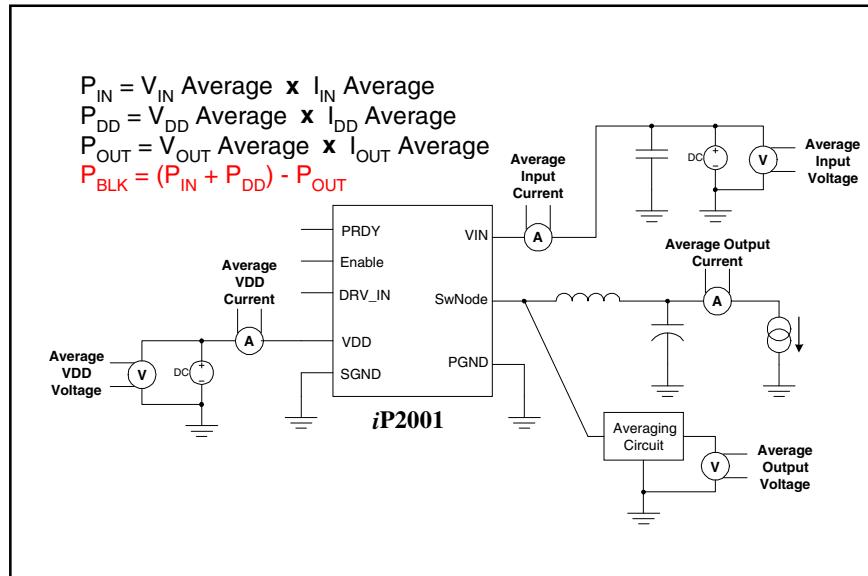


Fig 3. Power Loss Test Circuit

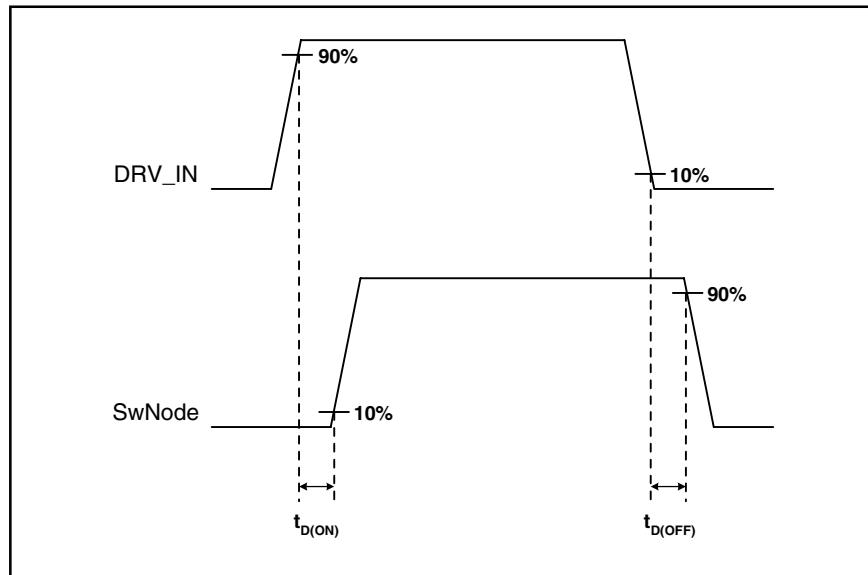
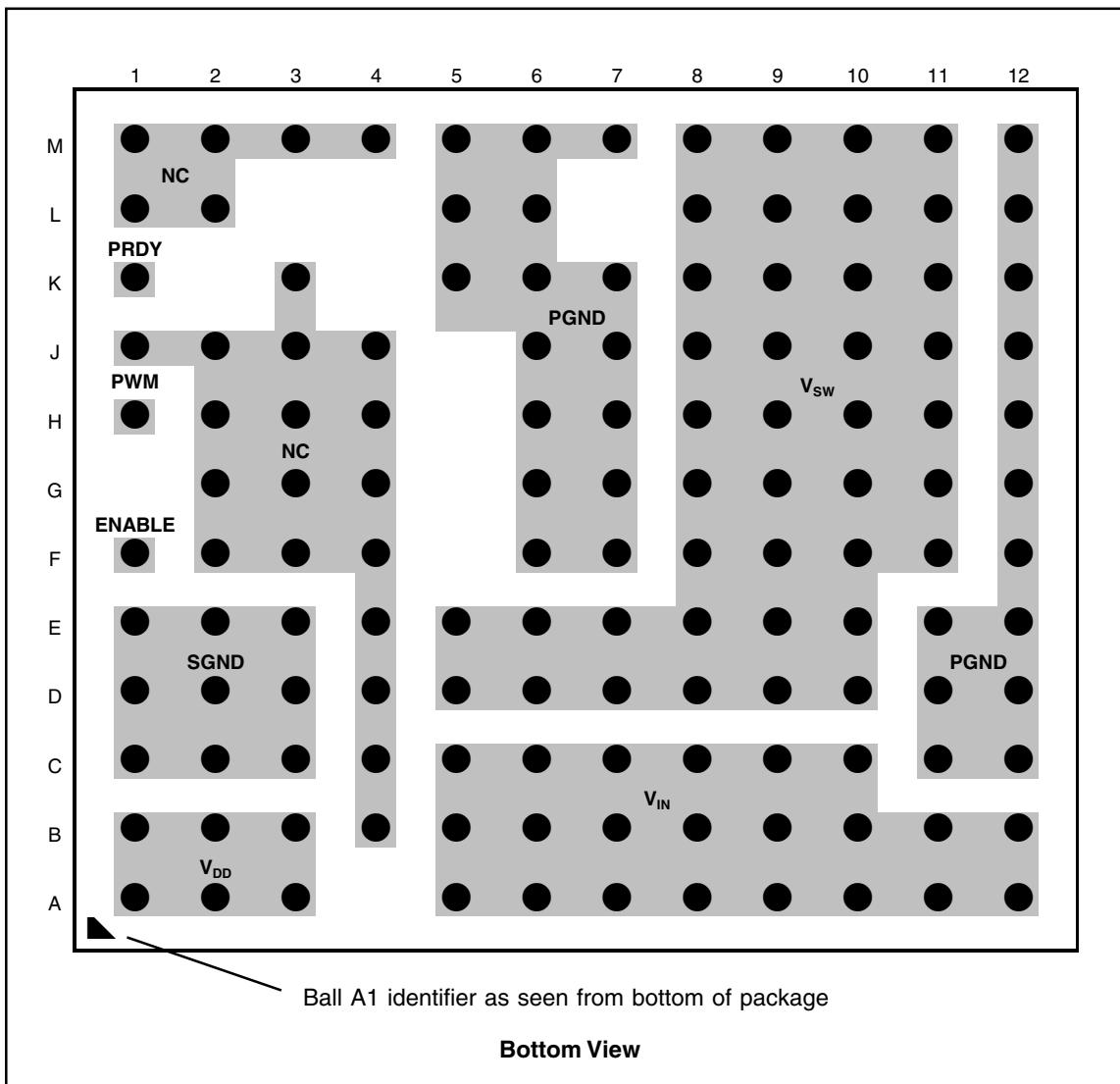
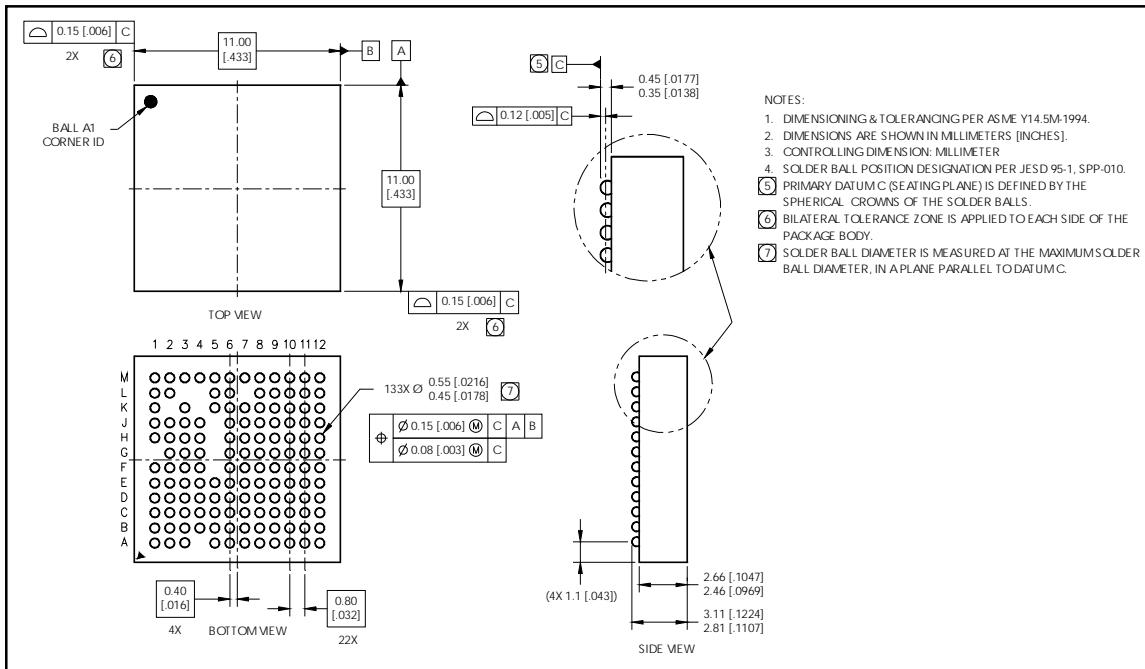


Fig 4. Timing Diagram



Pin Diagram



Mechanical Drawing

Refer to the following application notes for detailed guidelines and suggestions when implementing iPOWIR Technology products:

AN-1028: Recommended Design, Integration and Rework Guidelines for International Rectifier's iPOWIR Technology BGA Packages

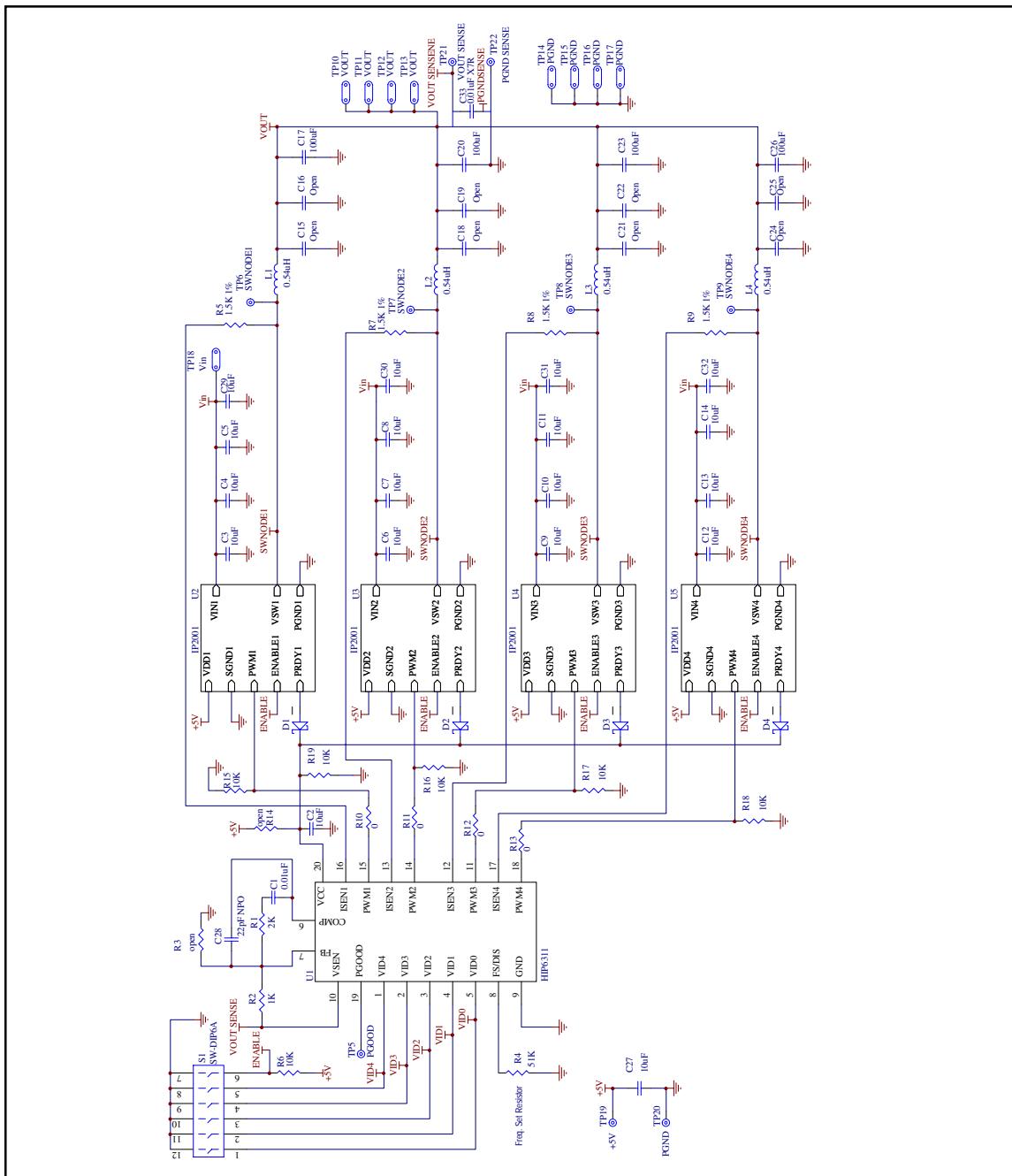
This paper discusses the assembly considerations that need to be taken when mounting iPOWIR BGA's on printed circuit boards. This includes soldering, pick and place, reflow, inspection, cleaning and reworking recommendations.

AN-1029: Optimizing a PCB Layout for an iPOWIR Technology Design

This paper describes how to optimize the PCB layout design for both thermal and electrical performance. This includes placement, routing, and via interconnect suggestions.

AN-1030: Applying iPOWIR products in your thermal environment

This paper explains how to use the Power Loss and SOA curves in the data sheet to validate if the operating conditions and thermal environment are within the Safe Operating Area of the iPOWIR product.



4-Phase Reference Design Schematic

| Designator | Value 1 | Value 2 | Type | Tolerance | Package | Mfr. 1 | Mfr. 1 Part No. | Mfr. 2 | Mfr. 2 Part No. |
|------------|---------|----------|------------|-----------|------------|-----------|-----------------|----------------|----------------------|
| C1 | 0.01uF | 50V | X7R | 10% | 0805 | TDK | C2012X7R1H103KT | SAMSUNG | CL21B103KBNC |
| C2 - C14 | 10uF | 16V | X5R | 10% | 1210 | TDK | C3225X5R1C106KT | Murata | GRM42-2 X5R 106K16 |
| C15 | - | - | - | - | - | - | - | - | - |
| C16 | - | - | - | - | - | - | - | - | - |
| C17 | 100uF | 6.3V | X5R | 10% | 2220 | TDK | C5750X5R0J107KT | MuRata | GRM44-1-X5R 107K 6.3 |
| C18 | - | - | - | - | - | - | - | - | - |
| C19 | - | - | - | - | - | - | - | - | - |
| C20 | 100uF | 6.3V | X5R | 10% | 2220 | TDK | C5750X5R0J107KT | MuRata | GRM44-1-X5R 107K 6.3 |
| C21 | - | - | - | - | - | - | - | - | - |
| C22 | - | - | - | - | - | - | - | - | - |
| C23 | 100uF | 6.3V | X5R | 10% | 2220 | TDK | C5750X5R0J107KT | MuRata | GRM44-1-X5R 107K 6.3 |
| C24 | - | - | - | - | - | - | - | - | - |
| C25 | - | - | - | - | - | - | - | - | - |
| C26 | 100uF | 6.3V | X5R | 10% | 2220 | TDK | C5750X5R0J107KT | MuRata | GRM44-1-X5R 107K 6.3 |
| C27 | 10uF | 16V | X5R | 10% | 1210 | TDK | C3225X5R1C106KT | Murata | GRM42-2 X5R 106K16 |
| C28 | 22pF | 50V | NPO | 5% | 0805 | TDK | C2012X7R1H220JT | ROHM | MCH215A220JK |
| C29 - C32 | 10uF | 16V | X5R | 10% | 1210 | TDK | C3225X5R1C106KT | Murata | GRM42-2 X5R 106K16 |
| C33 | 0.01uF | 50V | X7R | 10% | 0805 | TDK | C2012X7R1H103KT | SAMSUNG | CL21B103KBNC |
| D1 - D4 | 30V | 100mA | schottky | - | SOT23 | Central | CMPSH-3 | - | - |
| L1 - L4 | 0.54uH | 27A | ferrite | 20% | SMT | Panasonic | ETQP6F0R6BFA | Bi Technologie | HM73-30R60 |
| R1 | 2K | 1/8W | thick film | 5% | 0805 | ROHM | MCR10EZHF202 | - | - |
| R2 | 1K | 1/8W | thick film | 5% | 0805 | ROHM | MCR10EZHF102 | - | - |
| R3 | - | - | - | - | - | - | - | - | - |
| R4 | 51K | 1/8W | thick film | 5% | 0805 | ROHM | MCR10EZHW513 | - | - |
| R5 | 1.5K | 1/8W | thick film | 1% | 0805 | ROHM | MCR10EZHF1501 | KOA | RK73H2A1501F |
| R6 | 10K | 1/8W | thick film | 5% | 0805 | ROHM | MCR10EZHF103 | - | - |
| R7 - R9 | 1.5K | 1/8W | thick film | 1% | 0805 | ROHM | MCR10EZHF1501 | KOA | RK73H2A1501F |
| R10 - R13 | 0 | 1/8W | thick film | <50mΩ | 0805 | ROHM | MCR10EZHF000 | - | - |
| R14 | - | - | - | - | - | - | - | - | - |
| R15 - R19 | 10K | 1/8W | thick film | 5% | 0805 | ROHM | MCR10EZHF103 | - | - |
| U1 | 4.6-6 V | 0-1.850V | PWM IC | 0 - 70°C | 20 Ld SOIC | Intersil | HIP6311CB | - | - |
| U2 - U5 | - | - | - | - | 11x11x3mm | IR | iP2001 | - | - |

4-Phase Reference Design Bill of Materials